

DP 2520 Series

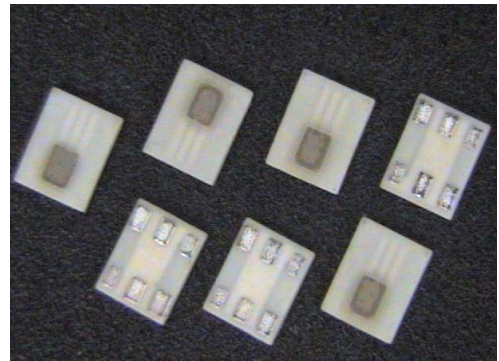
Multilayer Chip Diplexers

Features

- ❖ Monolithic structure including two band-pass filters with loss pole at adjacent passband.
- ❖ RoHS compliant

Applications

- ❖ 0.8 ~ 6 GHz wireless communication systems, including DECT/PACS/PHS/GSM/DCS phones, WLAN card, Bluetooth modules, etc.



Specifications

| Part Number | Passband (MHz) | Insertion Loss (dB) | Passband VSWR | Attenuation (dB) |
|----------------|----------------|---------------------|---------------|----------------------------|
| DP2520-N2455HA | 2400-2500 | 2.5 max. | 2.0 max. | 30 min. @ 824 ~ 915MHz |
| | | | | 30 min. @ 1545 ~ 1605MHz |
| | | | | 30 min. @ 1710 ~ 1910MHz |
| | | | | 25 min. @ 2170MHz |
| | | | | 35 min. @ 4800 ~ 5000MHz |
| | | | | 30 min. @ 7200 ~ 7500MHz |
| | 5150-5850 | 1.0 max. | 2.0 max. | 25 min. @ 2400 ~ 2500MHz |
| | | | | 20 min. @ 10300 ~ 11700MHz |

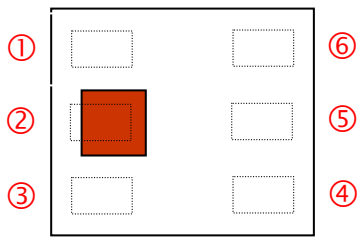
Q'ty/Reel (pcs) : 3,000
 Operating Temperature Range : -40 ~ +85 °C
 Storage Temperature Range : -40 ~ +85 °C
 Storage Period : 12 months max.
 Power Capacity : 500mW max.

Part Number

DP 2520 - N 2455 HA □ /LF
 ① ② ③ ④ ⑤ ⑥ ⑦

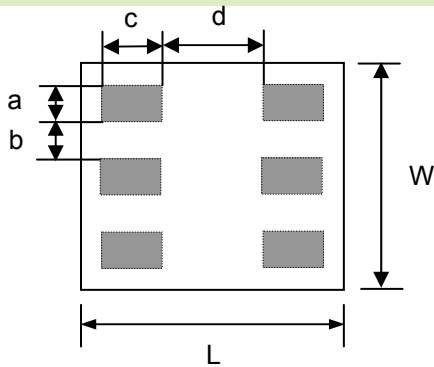
| | | | |
|----------------------|---------------|----------------------|---------------------------|
| ① Type | DP : Diplexer | ② Dimensions (L × W) | 2.5 × 2.0 mm |
| ③ Material Code | N | ④ Frequency Range | 2455 = 2400MHz /5500MHz |
| ⑤ Specification Code | HA | ⑥ Packaging | T: Tape & Reel B: Bulk |
| ⑦ Soldering | /LF=lead-free | | |

Terminal Configuration

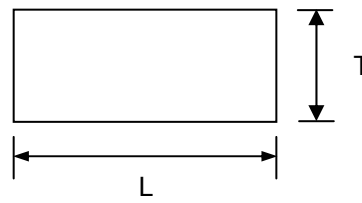


| No. | Terminal Name | No. | Terminal Name |
|-----|-------------------|-----|------------------|
| ① | Common Port | ④ | Lower Freq. Port |
| ② | GND | ⑤ | GND |
| ③ | Higher Freq. Port | ⑥ | GND |

Dimensions



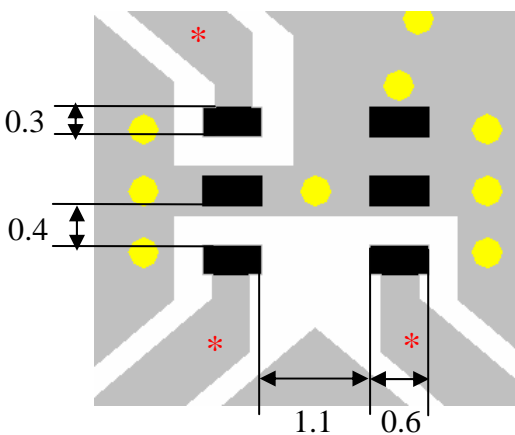
Unit : mm



Bottom View

Side View

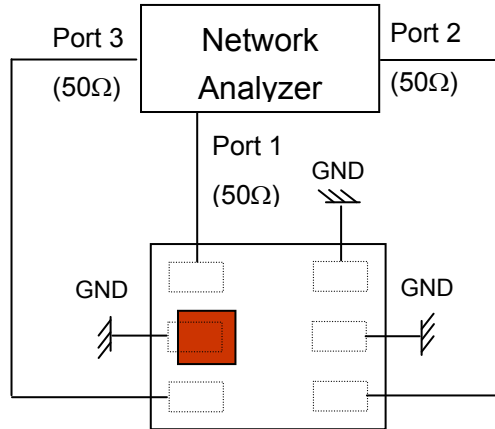
| Mark | L | W | T | a | b | c | d |
|------------|-----------|-----------|-----------|-----------|-----------|-----------|------------|
| Dimensions | 2.5 ± 0.2 | 2.0 ± 0.2 | 0.45 max. | 0.3 ± 0.1 | 0.4 ± 0.1 | 0.6 ± 0.1 | 1.1 ± 0.15 |



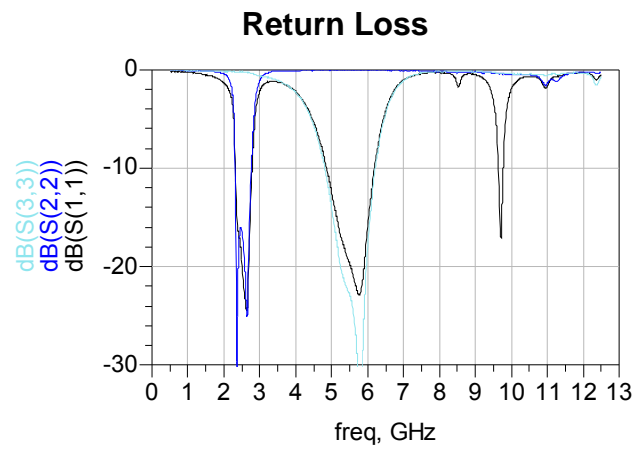
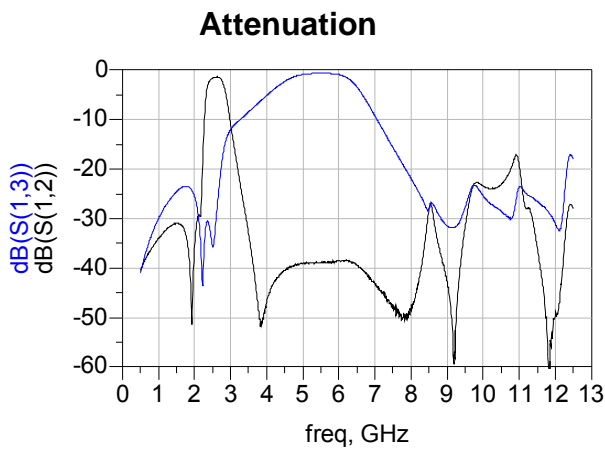
- Solder Resist
- Land
- Through-hole (ϕ 0.30)

* Line width should be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness.

Measuring Diagram



Typical Electrical Characteristics (T=25°C)

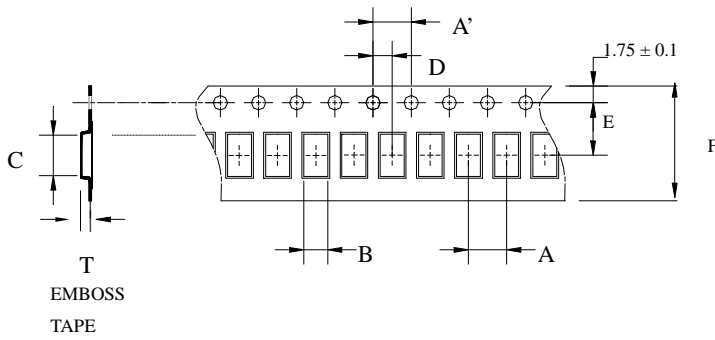


Notes

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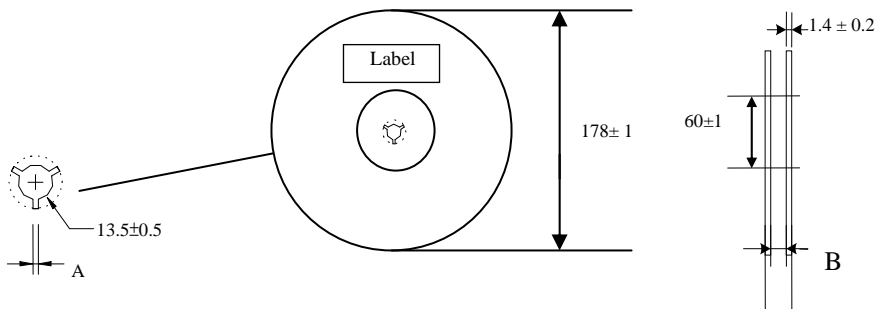
Taping Specifications

❖Tape Dimensions (Unit: mm) & Quantity



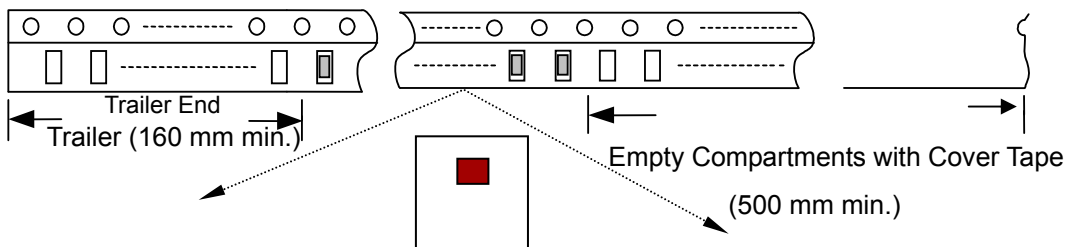
| Type | A | A' | B | C | D | E | F | T | Quantity/reel | Tape material |
|------|-------------|-------------|--------------|--------------|--------------|-------------|-------------|--------------|---------------|-----------------------|
| 2520 | 4.0± 0.1 | 4.0± 0.1 | 2.35± 0.1 | 2.80± 0.1 | 2.0± 0.05 | 3.5± 0.1 | 8.0± 0.1 | 0.6± 0.10 | 3,000pcs | Plastic (Embossed) |

❖Reel Dimensions (Unit: mm)

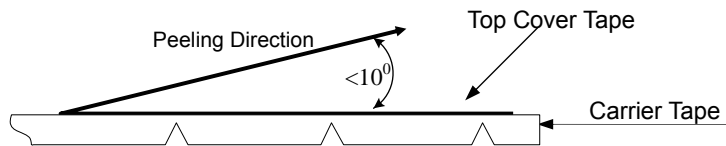


| Type | A | B |
|------|---------|---------|
| 2520 | 2.3±0.5 | 9.0±0.3 |

❖Leader and Trailer Tape



❖ **Peel-off Force**



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of 300 ± 10 mm/min .

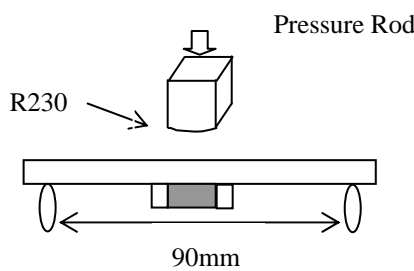
❖ **Storage Conditions**

- (1) Temperature: $5 \sim 35^{\circ}\text{C}$, relative humidity (RH): 45~75%.
- (2) Non-corrosive environment.

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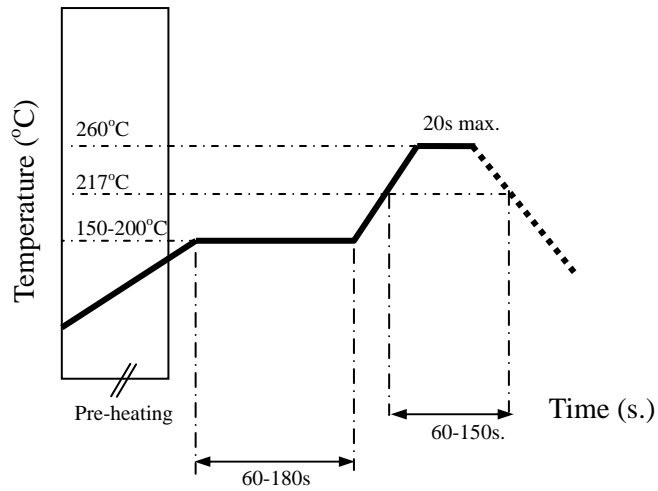
Mechanical & Environmental Characteristics

| Item | Requirements | Procedure |
|--|--|---|
| Solderability | <ol style="list-style-type: none"> No apparent damage More than 95% of the terminal electrode shall be covered with new solder | <ol style="list-style-type: none"> Preheat: $120 \pm 5^\circ\text{C}$ Solder: $245 \pm 5^\circ\text{C}$ for 5 ± 1 sec |
| Soldering strength (Termination Adhesion) | <ol style="list-style-type: none"> 1kg minimum | <ol style="list-style-type: none"> Solder specimen onto test jig. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction |
| Deflection (Substrate Bending) | <ol style="list-style-type: none"> No apparent damage | <ol style="list-style-type: none"> Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile. Apply a bending force of 2mm deflection  |
| Heat/Humidity Resistance | <ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test | <ol style="list-style-type: none"> Temperature: $85 \pm 2^\circ\text{C}$ Humidity: 90% ~ 95% RH Duration: 1000 ± 48hrs Recovery: 1-2hrs |
| Thermal shock (Temperature Cycle) | <ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test | <ol style="list-style-type: none"> One cycle/step 1 : $125 \pm 5^\circ\text{C}$ for 30 min step 2 : $-40 \pm 5^\circ\text{C}$ for 30 min No of cycles : 100 Recovery: 1-2 hrs |
| Low Temperature Resistance | <ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test | <ol style="list-style-type: none"> Temperature: $-40 \pm 5^\circ\text{C}$ Duration: 500 ± 24hrs Recovery: 1-2hrs |

Soldering Conditions

❖ Typical Soldering Profile for Lead-free Process

Reflow Soldering :



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Advanced Ceramic X Corp.

16 Tzu Chiang Road, Hsinchu Industrial District Hsinchu Hsien 303, Taiwan

TEL:886-3-5987008 FAX:886-3-5987001

E-mail: acx@acxc.com.tw <http://www.acxc.com.tw>